

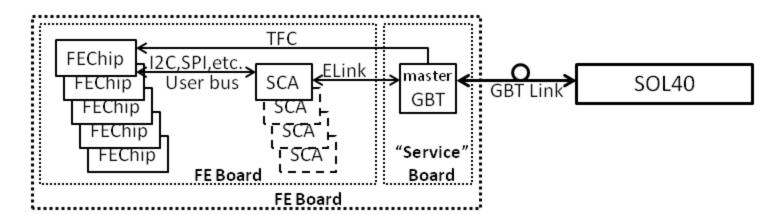
Experiment Control System & Electronics Upgrade

Hick ECS & Upgrade Electronics

- ECS Design doesn't change (in principle)
 - Same tools:
 - | Communications: DIM
 - Supervision: WinCC-OA (ex-PVSS II)
 - I Sequencing and Automation (FSM): SMI++
 - Same philosophy:
 - I Generic tools to describe the hardware (FwHw)
 - | Board Types -> "chips" -> registers => Boards
 - I Operation tools to Configure/Monitor boards
 - I "Recipes" for different configuration modes
 - I Stored in Configuration DB
 - New electronics will be interfaced like before

Electronics Interface

Interface to FE Electronics



- I Two Architectures envisaged:
 - I FE electronics in one single FE board
 - FE electronics accessed via a "Service" board (masterGBT <-> SCA via "long" Elink)

FE Board Protocols

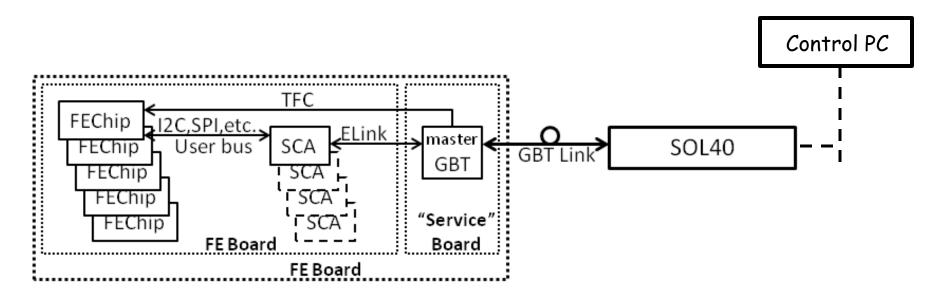
Interface to the FE Chips

- The GBT-SCA provides the following protocols:
 - 1 16 x I2C master controllers
 - 1 x JTAG master controller
 - $1 32 \times ADC$ channels (multiplexed)
 - 1 x Memory bus (32 bits) controller
 - $1.4 \times PIA$ (Parallel Interface Adapter) controllers
 - 1 x SPI (Serial Peripheral Interface) bus
 - 1 4 x DAC channels

Recommended protocols (for bulk transfers) are:

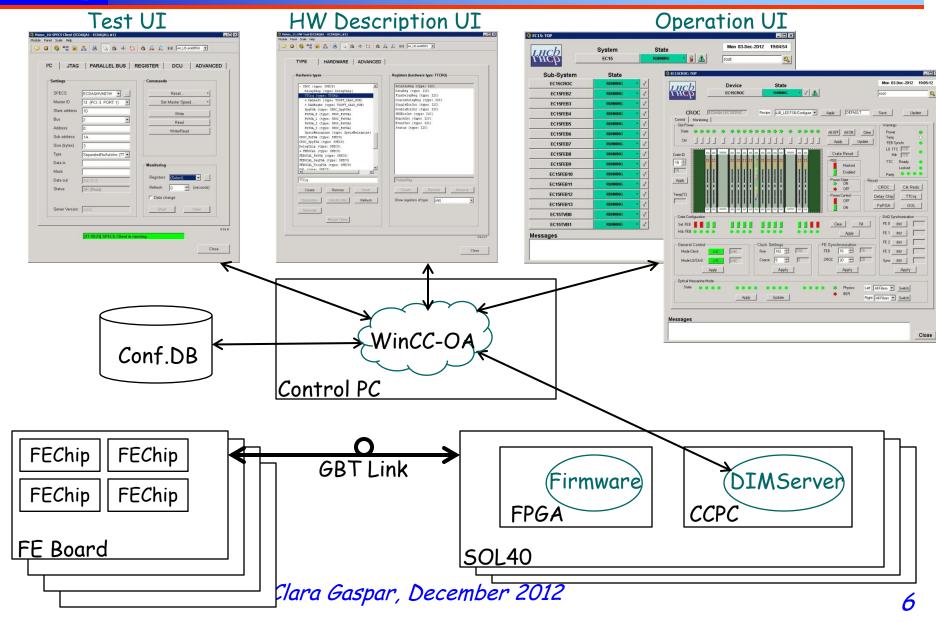
- I2C
- I SPI using independent chip selects (daisy chained SPI not allowed)

FE Addressing



FE Chip Register Address:

ECS FE Dataflow

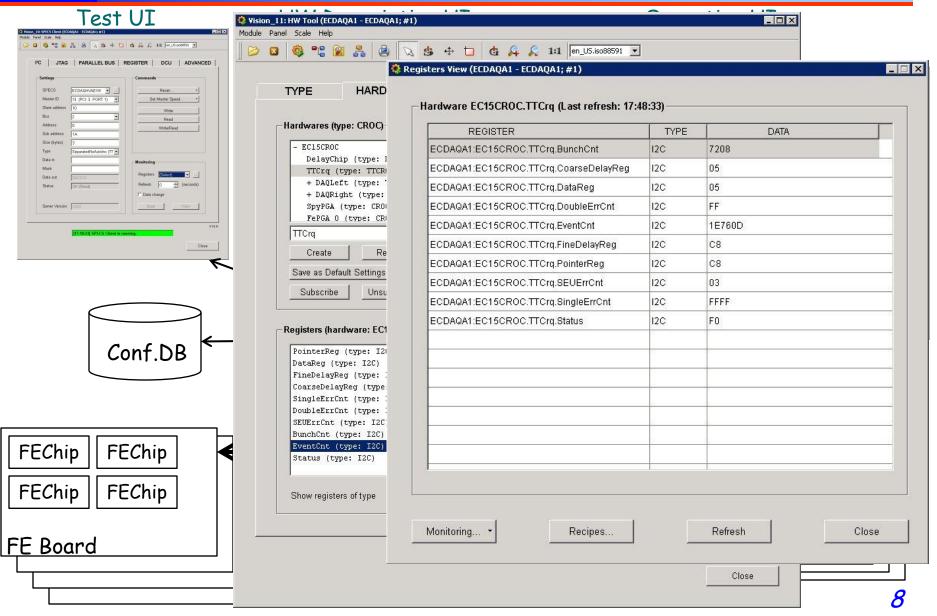


KKC ECS Software/firmware

Will be centrally provided:

- I The FPGA firmware for the SOL40 board
 - I Will prepare, send and receive the GBT-SCA frames for the various user protocols
 - I Should take load away from CCPC as much as possible
- Low-level libraries and command-line tools for the CCPC in the SOL40
 - I Will allow accessing the different FE chips
- I A DIM server running on the SOL40 CCPC
 - I Will implement higher-level commands to configure and monitor the FE chips
- A WinCC-OA component
 - I Providing the high-level description and access of all electronics components

Hick ECS Dataflow



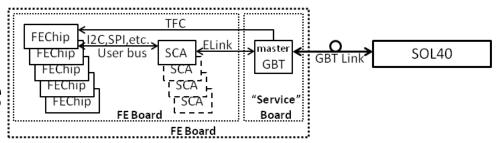
Hick ECS FE Design

1st Steps

- Understand the needs
- Identify bottlenecks



- 1. Sub-detector:
- 2. Number of GBT Links:
- Number of FE Boards (/Service Boards):
- 4. Number of SCA chips per masterGBT:
- 5. Number of User buses per SCA chip:
- Type of User buses used:
- 7. Number of "registers" per FE Board:
- 8. Data volume per FE Board for configuration:
- Data volume per FE Board for monitoring (and how often):



Kick Scalability & Efficiency

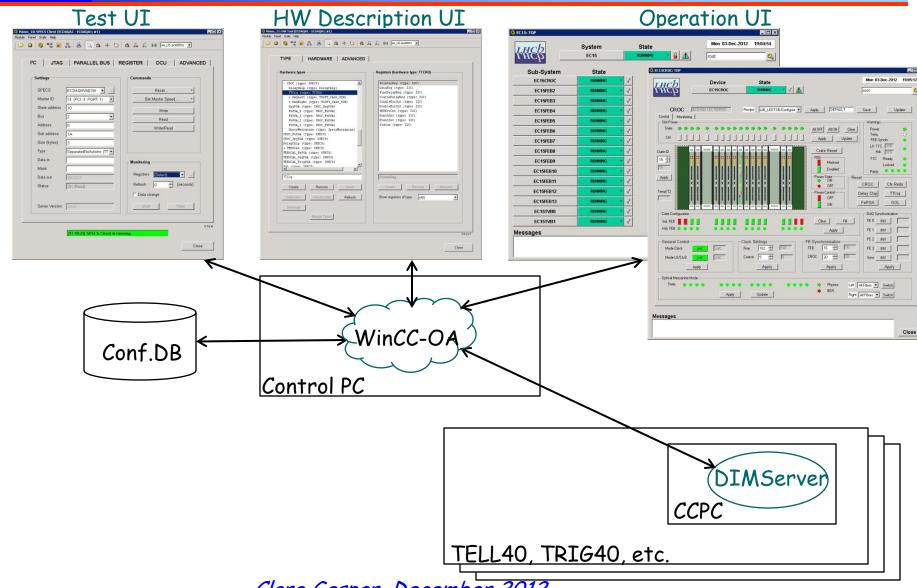
Configuration and Monitoring speed

- Is not just data size / bandwidth
- Depends on:
 - I How the data is distributed, for ex.:
 - I A few large registers or many small ones
 - I Are blocking operations needed, for ex.:
 - A register needs to be set and read-back before configuring the next one
 - I or read-modify-write operations that need to be done by the back-end
 - Which user protocol is used and how it is used, for ex.:
 - I Some I2C devices needed an extra I2C operation to write a subaddress before the block of data could be written
 - I Some did not implement auto-increment so block transfer could not be used
- I Try to influence hw design early enough...

HEB Board Interface

- Physically only one board type (ATCA40/AMC40): TELL40, S-ODIN, TRIG40, SOL40
 - But logically different types (different "registers")
- Similar Tools will be provided centrally:
 - Low-level libraries and command-line tools for the CCPC in the board
 - I Will allow accessing the different registers (PCIexpress)
 - I A DIM server running on the CCPC
 - I Will implement higher-level commands to configure and monitor the board components
 - A WinCC-OA component
 - I Providing the high-level description and access of all electronics components

KHCK ECS BE Dataflow



KKC Infrastructure Control

- The control & monitoring of the crates (& boards) will also be provided centrally
 - ATCA provides a standard for the control and monitoring of power, voltages, temperatures etc.:
 -> IPMI
 - I A WinCC-OA component will be provided.